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S/N 09/854,539

TECHNOLOGY CENTER R3700

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Steven Towle

Examiner: Ginette Peralta

Serial No.:

09/854,539

Group Art Unit: 2814

Filed:

May 14, 2001

Docket: 884.415US1

Title:

POLYMERIC ENCAPSULATION MATERIAL WITH FIBROUS FILLER FOR

USE IN MICROELECTRONIC CIRCUIT PACKAGING

RESPONSE TO RESTRICTION REQUIREMENT UNDER 37 C.F.R. § 1.142

Commissioner for Patents Washington, D.C. 20231

In response to the Restriction Requirement mailed January 21, 2003, Applicant elects, *without* traverse, claims 1-3, 5, and 9-11. Applicant identifies the alleged species set forth in the Office Action:

a. Microelectronic device comprising a package core and a microelectronic die located within an opening in the package core, and a fiber reinforced encapsulation material within the opening etc.

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REMARKS

Applicant respectfully asserts that the claims are now in condition for examination. The Examiner is invited to contact Applicant's Representative John Greaves at 801/278-9171 or the below signed attorney if there are any questions regarding this Response or if prosecution of this application may be assisted thereby.

Respectfully submitted,

STEVEN TOWLE

By his Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A. P.O. Box 2938 Minneapolis, MN 55402

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Date Feb. 21, 2003 By Conn

Ann M. McCrackin Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on this 21st/day of February, 2003.

Anne Richards Name

Signature